

Title (en)

Polishing apparatus and polishing method for silicon wafers

Title (de)

Vorrichtung und Verfahren zum Polieren von Halbleiterscheiben

Title (fr)

Machine et procédé de polissage de plaquettes semi-conductrices

Publication

EP 0798079 A3 19980325 (EN)

Application

EP 97104697 A 19970319

Priority

- JP 6799796 A 19960325
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Abstract (en)

[origin: EP0798079A2] A polishing apparatus and a polishing method of semiconductor wafers are provided, whereby heavy metal contamination of semiconductor wafers can be prevented effectively in a polishing process. A polishing apparatus of semiconductor wafers including a turn table assembly having a rotatably fixed turn table and a polishing slurry tank for storing polishing slurry to be supplied onto the turn table with a polishing slurry supplying member, wherein the polishing slurry supplying member is provided with means for eliminating heavy metal ions from the polishing slurry. <IMAGE>

IPC 1-7

B24B 55/03; **B24B 37/04**

IPC 8 full level

B24B 57/00 (2006.01); **B24B 55/03** (2006.01); **B24B 57/02** (2006.01); **H01L 21/304** (2006.01)

CPC (source: EP)

B24B 37/04 (2013.01); **B24B 55/03** (2013.01)

Citation (search report)

- [Y] US 5087372 A 19920211 - TOYOMOTO KAZUO [JP], et al
- [A] EP 0639534 A2 19950222 - EBARA CORP [JP]
- [Y] PATENT ABSTRACTS OF JAPAN vol. 017, no. 102 (C - 1031) 2 March 1993 (1993-03-02)
- [A] PATENT ABSTRACTS OF JAPAN vol. 009, no. 045 (C - 268) 26 February 1985 (1985-02-26)

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EP 0798079 A2 19971001; **EP 0798079 A3 19980325**; **EP 0798079 B1 20001018**; DE 69703312 D1 20001123; DE 69703312 T2 20010222; JP 3384530 B2 20030310; JP H09314466 A 19971209; MY 132494 A 20071031

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